



TFW #8

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Brown, et al.	Customer No:	32107
Assignee:	Microfabrica Inc.	Docket No:	P-US075-A-MG
Title:	Miniature RF and Microwave Components and Methods for Fabricating Such Components		
Application No:	10/607,931	Filing Date:	June 27, 2003
Examiner:	Glenn, Kimberly E.	Group Art No:	2817

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

May 5, 2006

INFORMATION DISCLOSURE COVER LETTER

Dear Sir:

Please find enclosed herewith a Transmittal of Information Disclosure Statement, an Information Disclosure Statement, and copies of non-U.S. Patent references.

Non-English language reference RU 2046469 is being cited solely as it was cited as a reference in the PCT counterpart (WO 2004/004061) to the present applicant.

All three of the non-English language Japanese references are being cited herein solely because they were cited against WO 2000/039854 which in turn was cited against the European counterpart (EP 0313058) to the present application

Respectfully submitted,

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I certify that this paper and any indicated enclosure(s) and fee(s) are being deposited on May 5, 2006 with the U.S. Postal Service as first class or priority mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313.

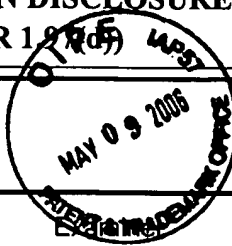
Elizabeth Brown

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT

(Under 37 CFR 1.97(c))

Docket No.
P-US075-A-MG

In Re Application Of: Brown et al.



Application No.	Filing Date	Inventor	Customer No.	Group Art Unit	Confirmation No.
10/607,931	June 27, 2003	Glenn, Kimberly E.	32107	2817	

Title: Miniature RF and Microwave Components and Methods for Fabricating Such Components

Address to:
Commissioner for Patents

The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(c), and on or before payment of the issue fee, and is accompanied by the Statement as specified in 37 CFR 1.97(e) and the fee set forth in 37 CFR 1.17(p).

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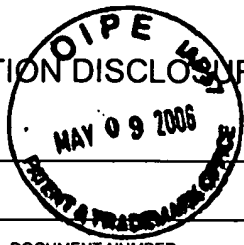
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INFORMATION DISCLOSURE CITATION



ATTY DOCKET NO.
P-US075-A-MG

APPLICATION NO.
10/607,931

APPLICANT(S)
Brown, et al.

FILING DATE
June 27, 2003

GROUP ART UNIT
2817

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	1	4,021,789	05/03/1977	Furman, et al.	365	182	
	2	4,127,831	11/28/1978	Gordon P. Riblet	333	10	
	3	4,958,222	09/18/1990	Kabushiki Kaisha Toshiba	357	84	
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	5	5,426,399	06/20/1995	Matsubayashi, et al.	333	1	
	6	6,027,630	02/22/2000	Adam L. Cohen	205	135	
	7	6,572,742	06/03/2003	Adam L. Cohen	204	297.5	

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*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	8	2003/0127336	07/10/2003	Cohen, et al.	205	118	
	9	2003/0221968	12/04/2003	Cohen, et al.	205	118	
	10	2003/0222738	12/04/2003	Brown, et al.	333	160	
	11	2003/0234179	12/25/2003	Christopher A. Bang	205	118	
	12	2004/0000489	01/01/2004	Zhang, et al.	205	118	
	13	2004/0004001	01/08/2004	Cohen, et al.	205	118	
	14	2004/0004002	01/08/2004	Thompson, et al.	205	118	
	15	2004/0007468	01/15/2004	Cohen, et al.	205	118	
	16	2004/0065550	04/08/2004	Gang Zhang	205	135	
	17	2004/0020782	02/05/2004	Cohen, et al.	205	220	
	18	2004/0065555	04/08/2004	Gang Zhang	205	118	

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

INFORMATION DISCLOSURE CITATION				ATTY DOCKET NO. P-US075-A-MG		APPLICATION NO. 10/607,931	
				APPLICANT(S) Brown, et al.			
				FILING DATE June 27, 2003		GROUP ART UNIT 2817	
FOREIGN PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	Translation Yes/No
	19	EP 0313058	04/26/1989	Wong, Mon N.	H01Q	3/40	N/A
	20	JP 8-274167	10/18/1996				No - Abstract only
	21	JP 1-125956	05/18/1989				No - Abstract only
	22	JP 6-232217	08/19/1994				No - Abstract only
	23	RU 2046469	10/20/1995		H01P	5/18	No - Abstract only
	24	WO 2000/39854	07/06/2000	Kwon, et al.	H01L	27/00	N/A
	25	WO 2003/049514	06/12/2003	Brown, et al.	H05K	3/00	N/A
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
	26	Cohen, et al., "EFAB: Batch Production of Functional, Fully-Dense Metal Parts with Micron-Scale Features", Proc. 9th Solid Freeform Fabrication, The University of Texas at Austin, August 1998, pg. 161.					
	27	Adam L. Cohen, et al., "EFAB: Rapid, Low-Cost Desktop Micromachining of High Aspect Ratio True 3-D MEMS", Proc. 12th IEEE Micro Electro Mechanical Systems Workshop, IEEE, Jan 1999, pg. 244.					
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	29	Adam L. Cohen, "3-D Micromachining by Electrochemical Fabrication", Micromachine Devices, March 1999, pgs. 6-7.					
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	32	Adam L. Cohen, et al., "EFAB: Low-Cost, Automated Electrochemical Batch Fabrication of Arbitrary 3-D Microstructures", Micromachining and Microfabrication Process Technology, SPIE 1999 Symposium on Micromachining and Microfabrication, September 1999.					
	33	F. Tseng, et al., "EFAB: High Aspect Ratio, Arbitrary 3-D Metal Microstructures Using a Low-Cost Automated Batch Process", MEMS Symposium, ASME 1999 International Mechanical Engineering Congress and Exposition, November, 1999.					
	34	Adam L. Cohen, "Electrochemical Fabrication (EFABTM)", Chapter 19 of the MEMS Handbook, edited by Mohamed Gad-El-Hak, CRC Press, 2002, pgs. 19/1 - 19/23.					
	35	J. A. Bishop, et al., "Monolithic Coaxial Transmission Lines for mm-wave ICs", High Speed Semiconductor Devices and Circuits, 1991., Proceeding IEEE/Cornell Conference on Advanced Concepts in Ithaca, NY, USA 5-7 AUG. 1991, pgs. 252-260.					
	36	Jeong Inho, et al., "Monolithic Implementation of Air-Filled Rectangular Coaxial Line", Electronics Letters, IEE Stevenage, GB, Vol. 36, No. 3, 3 February 2000, pgs. 228-230.					
EXAMINER				DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>							